

One-NAND Code Information(1/2)

Last Updated : November 2008

K **F** X X X X X X X X - X X X X X X X
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

1. Memory (K)

2. OneNAND : F

3. Small Classification

G : De-Muxed
H : De-Muxed 2 Die Stack
W : De-Muxed 4 Die Stack w/ Dual nCE
M : Muxed
N : Muxed 2 Die Stack
K : Muxed 4 Die Stack w/ Dual nCE

4~5. Density

12 : 512M	28 : 128M
56 : 256M	1G : 1G
2G : 2G	4G : 4G
8G : 8G	AG : 16G

6. Technology

1 : SLC (OneNAND)
H : MLC (Flex-OneNAND)

7. Organization

6 : x16

8. Vcc

D : 2.5V/2.7V (2.4V~3.0V)
Q : 1.8V (1.7V~1.95V)
U : 3.0V/3.3V (2.7V~3.6V)

9. Mode

0 : 512 Byte Page
1 : 1K Byte Page
2 : 2K Byte Page
4 : 4K Byte Page

10. Generation

M : 1st Generation
A : 2nd Generation
B : 3rd Generation
C : 4th Generation

11. "—"

12. Package (AG01000 PKG SPEC Reference)

A : FBGA (Lead-Free, Halogen-Free)
B : FBGA (Lead-Free, Halogen-Free, OSP)
D : FBGA (Lead-Free)

13. Temp

C : Commercial
E : Extend
I : Industrial
0 : NONE

14. Bad Block

0 : NONE
B : Include Bad Block
D : Daisychain Sample

15. Speed

0 : Reserved
5 : 54MHz
6 : 66MHz
8 : 83MHz

One-NAND Code Information(2/2)

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<u>K</u>	<u>F</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>-</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

16. Packing Type

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other (Tray, Tube, Jar)	0 (Number)
	Stack	S
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

17~18. Customer "Customer List Reference"